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**TITLE:** IN-PRINT METHOD AND IN-PRINT DEVICE  
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**INVENTOR-INFORMATION:**

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**ABSTRACT:**

**PROBLEM TO BE SOLVED:** To provide an in-print method and an in-print device with which a mold pattern can be transferred all over the press plane with high uniformity by equally pressing the mold pattern of a wide area.

**SOLUTION:** In the in-print method and the in-print device for transferring a mold pattern 4 on a film 6 for wafer working by pressing the mold pattern 4 formed on a mold wafer 3 on the film 6 for wafer working formed on a wafer 5, the height of the mold pattern 4 in the pressing direction is decreased from the center of the press plane to the peripheral edge, and non-uniformity in a pressure on the press plane in the case of pressing is lowered in comparison with the case of no decrease in the height.

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